## **REMARKS/ARGUMENTS**

The applicant's attorneys appreciate the Examiner's thorough search and remarks.

Claims 1 and 11 have been rejected as anticipated by Potter et al., U.S. Patent No. 5,426,263. Reconsideration is requested.

Potter et al. show a device which includes a leadless component 10 disposed between two circuit boards 30, 32. The leadless component 10 shown by Potter et al. is a package which includes a semiconductor IC 20 disposed on a substrate 22 and encapsulated by an enclosure 24.

On the other hand, claims 1 and 11 call for a semiconductor die which is electrically and mechanically connected directly to conductive pads of a circuit board or a thermally conductive substrate. Specifically, claims 1 and 11 call for a layer of conductive adhesive to be interposed between the contacts of a semiconductor die and the conductive pads of a circuit board or a thermally conductive substrate. Potter et al. neither show nor suggest such a combination of elements. Reconsideration is requested.

Each of the remaining claims is a dependent claim which depends from one of claims 1 and 11. Each dependent claim includes other limitations, which in combination with those of its base claim, are not shown or suggested by the art of record. Reconsideration is requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 14, 2004:

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Signature

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